



# Forward Automation

## Automatic Pattern Process Plating Line

Pattern plating, as the name implies, involves masking off most of the copper surface and plating only the traces and pads of the circuit pattern. Due to the reduced surface area, a much smaller capacity current source is generally needed. Further, when using contrast reversing photopolymer dry-film plating masks (the most common type), a positive image of the circuit is all that is needed. For many prototype PCBs, this artwork can be reliably produced on a relatively inexpensive laser printer or pen plotter. Pattern plating consumes less copper from the anode bank and requires that less copper be removed during etching reducing bath analysis and maintenance. The downside of the technique is that it requires that the circuit pattern be plated with either tin/lead or an electrophoretic resist material prior to etching and then stripped prior to soldermask application. This increases the complexity and adds another set of wet chemical baths to the process.

This Pattern Copper Process Plating line can be made by the requirement of the PCB specification and production capacity from clients.

